

Product Change Notification / LIAL-29JCGD899

Date:

05-Nov-2020

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4439 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 8L DFN (4x4x0.9mm) package at MMT assembly site

Affected CPNs:

LIAL-29JCGD899_Affected_CPN_11052020.pdf LIAL-29JCGD899_Affected_CPN_11052020.csv

Notification Text:

PCN Status: Initial notification.

PCN Type: Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 8L DFN (4x4x0.9mm) package at MMT assembly site

Pre Change: Using gold (Au) bond wire

Post Change: Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	Microchip Technology Thailand (MMT)	Microchip Technology Thailand (MMT)			
Wire material	Au	CuPdAu			
Die attach material	3280	3280			
Molding compound material	G700LTD	G700LTD			
Lead frame material	A194	A194			

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

December 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2020				December 2020				
Workweek	45	46	47	48	49	51	51	52	53
Initial PCN	Х								
Issue Date									
Qual Report								Х	
Availability								^	
Final PCN								Х	
Issue Date								^	

Method to Identify Change:

Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan

Revision History: November 5, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-29JCGD899_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-29JCGD899 - CCB 4439 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 8L DFN (4x4x0.9mm) package at MMT assembly site

Affected Catalog Part Numbers (CPN)

PIC12F675-E/MD PIC12F675-I/MD176 PIC12F675-I/MD PIC12F675T-E/MD PIC12F629-E/MD PIC12F629-I/MD PIC12F629T-I/MD PIC12F629T-E/MD PIC12F683-E/MD PIC12F683-I/MD PIC12F683T-I/MD PIC12F635-I/MD PIC12F635T-I/MD070 PIC12F635T-I/MD073 PIC12F635T-I/MD PIC12F615-E/MD PIC12F615-I/MD PIC12F615-H/MD PIC12F615T-I/MD029 PIC12F615T-I/MD PIC12HV615-I/MD PIC12F609-E/MD PIC12F609-I/MD PIC12F609T-I/MD